

Space Parts Working Group

Doubletree Torrance South Bay
Torrance, Calif.
May 5–6, 2009

Tuesday May 5

- 7:00 Registration and continental breakfast
- 8:00 **Welcome and Opening Remarks**
M. Cohen, The Aerospace Corporation
D. Davis, Space and Missile Systems Center
- 8:10 **Keynote Address**
D. Gorney, Senior Vice President, The Aerospace Corporation
- 8:40 **Space and Missile Systems Center Update**
D. Davis, Space and Missile Systems Center
- 9:00 **NASA Update**
M. Sampson and K.LaBel, NASA
- 9:35 **Missile Defense Agency Parts Plan Update**
B. Birdsong, Missile Defense Agency
- 10:00 Break
- 10:10 **Radiation Hardened Space Electronics Update**
K. Hunt, Air Force Research Laboratories
- 10:30 **NRO Counterfeit Policy and Temporary Enterprise Counterfeit Analysis Center**
Maj. D. Laird, Chief, Product Assurance Branch, National Reconnaissance Office
- 10:50 **European Space Agency Update**
R. de Marino, European Space Agency
- 11:10 **Analysis and Certification of Standard Reference Material (Tin/Lead)**
J. Sieber, Chemical Science and Technology Laboratory, National Institute of Standards and Technology
- 11:30 **Standardized Testing for prohibited Materials by Instrumental Analysis**
T. Hester, Raytheon
- 11:50 Lunch (on your own)

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Tuesday May 5 (continued)

- 12:50 **Supplier Update**
J. Vargas, Semtech Corporation
- 1:05 **Japanese Space Exploration Agency Update**
K. Shinozaki, Japanese Space Exploration Agency
- 1:20 **Supplier Roadmap**
A. Oullet, STMicroelectronics
- 1:35 **Aeroflex HI-REL Components Supplier Roadmap**
M. Mcnulla, Aeroflex Hi-REL Components
- 1:50 **Supplier Update**
R. Pragasam, National Semiconductor
- 2:05 **Contractor Audit and Performance Tracking Database**
Maj. D. Laird, Chief, Product Assurance Branch, National Reconnaissance Office
- 2:20 **Texas Instruments Space Products Expansion QMLV Status and Road Map**
B. Rhoton and J. Salzman, Texas Instruments
- 2:35 **Microcircuit Update**
D. Peters, The Aerospace Corporation
- 2:50 Break
- 3:00 **Fiber Optic Systems in Space, Missile, and Avionic Applications**
C. Tabbert, Ultra Communications
- 3:15 **Hybrid Update**
J. Sokol, The Aerospace Corporation
- 3:35 **Supplier Update**
G. Panning, Honeywell
- 3:50 **Supplier Update**
K. O'Neill, Actel Corporation

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Tuesday May 5 (continued)

- 4:05 **Field Programmable Gate Arrays Update**
L. Harzstark, The Aerospace Corporation
- 4:25 **Supplier Update**
D. Strobel, Space Micro
- 4:40 **Passive Components Update**
M. Garcia, The Aerospace Corporation
- 4:55 **Supplier Update**
R. Chesley, Intersil
- 5:15 No-Host Networking Reception

Wednesday, May 6

- 7:00 Registration and continental breakfast
- 8:00 **Welcome**
D. Davis, Space and Missile Systems Center
- 8:05 **HI-REL Laboratories DPA Summary Report**
T. Devaney, HI-REL Laboratories
- 8:25 **The Use of Ultrasonic Imaging to Determine Flaw Sizes in BaTiO Capacitors**
C. Pollock, Presidio Capacitors
- 8:45 **Defense Supply Center Columbus Update**
A. Barone, Defense Supply Center Columbus
- 9:05 **Supplier Update**
R. Albarian, Linear Technology
- 9:20 **Hybrid Supplier Update**
G. Overend and P. Musil, M.S. Kennedy

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Wednesday, May 6 (continued)

- 9:40 **Supplier Update**
K. Karlsen, Microsemi Corporation
- 10:00 Break
- 10:10 **IR to Embrace the Hybrid Requirements of the Aerospace TOR**
M. Toland, International Rectifier
- 10:30 **TOR Compliant D.C. to D.C. Converters**
D. Sable, VPT Inc.
- 10:50 **The Advanced Technologies Group Foundational and Communications Division
Radiation Hardened Microelectronics Program: a Status Report**
L. Cohn, National Reconnaissance Office
- 11:10 **Column Grid Arrays**
R. Winslow, Six Sigma
- 11:30 **Connector Plating Concerns**
M. Clark, Tyco
- 11:45 **Hermetic Column Grid Array Packaging Reliability**
K. Sturcken, BAE System
- 12:00 Lunch (on your own)
- 1:00 **Supplier Update**
M. Pitka, Sensitron
- 1:20 **Supplier Update**
C. Hafer, Aeroflex
- 1:40 **Supplier Update**
J. Fabula, Xilinx, Inc.
- 2:00 **Supplier Update**
B. Barfield, Analog Devices

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Wednesday, May 6 (continued)

- 2:20 **Supplier Update**
C. Caletika, Micropac
- 2:40 **Semiconductor Update**
M. Cohen, The Aerospace Corporation
- 2:55 Break
- 3:05 **QPL Qualification Update**
D. Guy, SSDI
- 3:20 **Fundamental Research in the Hermeticity of Microelectronic Packages**
K. Rink, University of Idaho, Department of Mechanical Engineering
- 3:35 **Radiation Effects Testing to Meet Expanded Mission Requirements**
J. Benedetto, Radiation Assured Devices
- 3:50 **IR Supplier Roadmap Update**
M. Toland, International Rectifier
- 4:05 **Counterfeit Mitigation Procedure Employed by a Distributor**
T. Sharp, SMT Corporation
- 4:25 **Introduction of 1N7068**
D. Guy, SSDI
- 4:40 **Wrap-up**
D. Davis, Space and Missile Systems Center
- 5:00 **Please note: a special session with Aeroflex Weinschel is planned for Wednesday, May 6. The speaker and specific presentation time are still TBD. Additional details will be provided as the conference date approaches.**
- 7:00 Adjourn